

**LEX eIO extension SBCs** with multi-function extension cards provide faster development schedules in an efficient and cost-effective way.

LEX eIO extension solutions cover 3.5" SBC, Pico-ITX SBC, various expansion modules, as well as full systems for complete embedded solutions.



L2L002 + 2I385EW



L2L002 + 2I390CW

**Lex** SYSTEM®





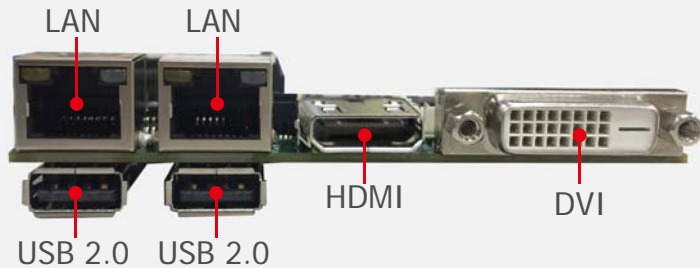
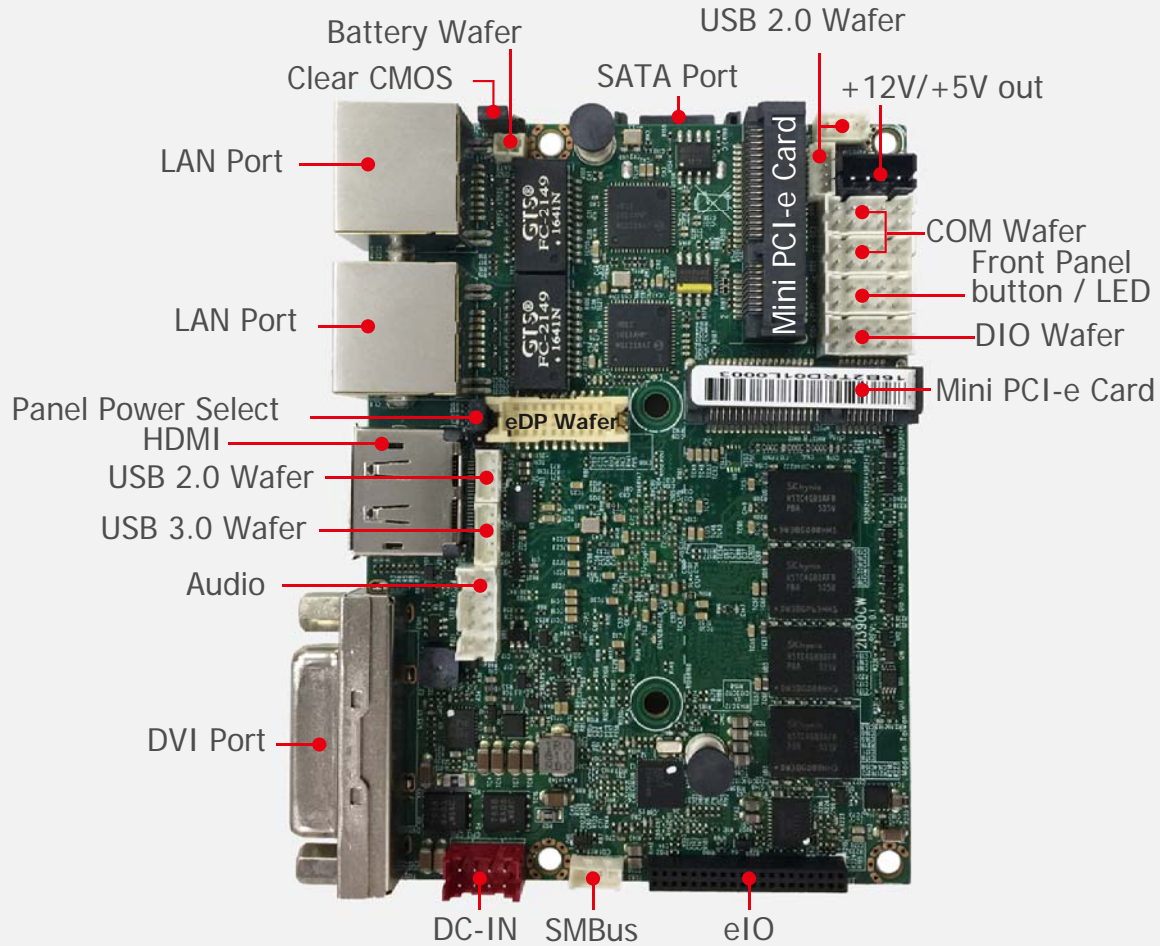


## Flexible Expansion via LEX eIO SBCs:

**2I390CW/2I390CW/2I385EW/2I386EW/3I610DW & eIO cards/modules**

LEX Computech released series of the innovative eIO SBCs which are integrated with eIO (2 x PCIe + USB) expansion function. LEX eIO SBCs: 2I390CW / 2I392CW / 2I385EW / 2I386EW / 3I610DW are based on the Intel® Bay Trail & Apollo Lake / Skylake-U / Kaby Lake-U processors, integrated 2~5 x GbE LAN, 4~5 x USB, 2~4 x COM Port, VGA, HDMI, eDP & DVI display interface that offer the ideal platforms for high performance applications in Machine Vision, Medical devices, POS/Kiosk, Automation, Military & Industrial facilities.

# Function MAP



21390CW

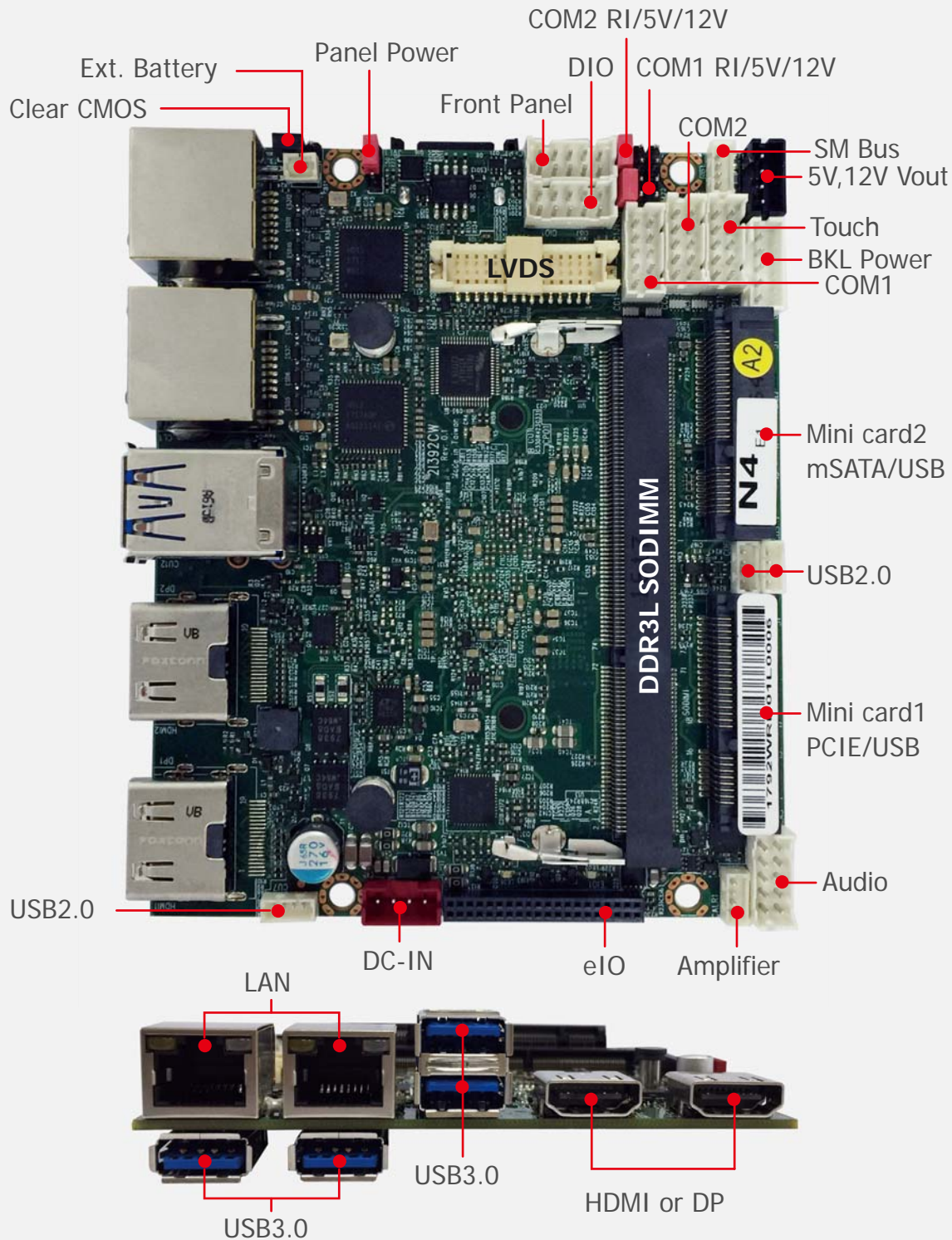
Compact solution with Rich Expansion for vertical application

- Intel® Apollo Lake N4200 / N3350 / E3950 SoC CPU / chipset
- On board DDR3L 4GB
- Display: eDP, HDMI & DVI
- 2 x GbE, 2 x Mini PCIe, 2 x USB 3.0, 3 x USB 2.0
- 4DI/4DO, HD audio, 2 x COM, Lex eIO: 2 x PCIe + USB
- Wide Range DC IN +9~36V
- Wide temperature support of -20°C ~ 70°C
- Support 4K UHD resolution content





# Function MAP



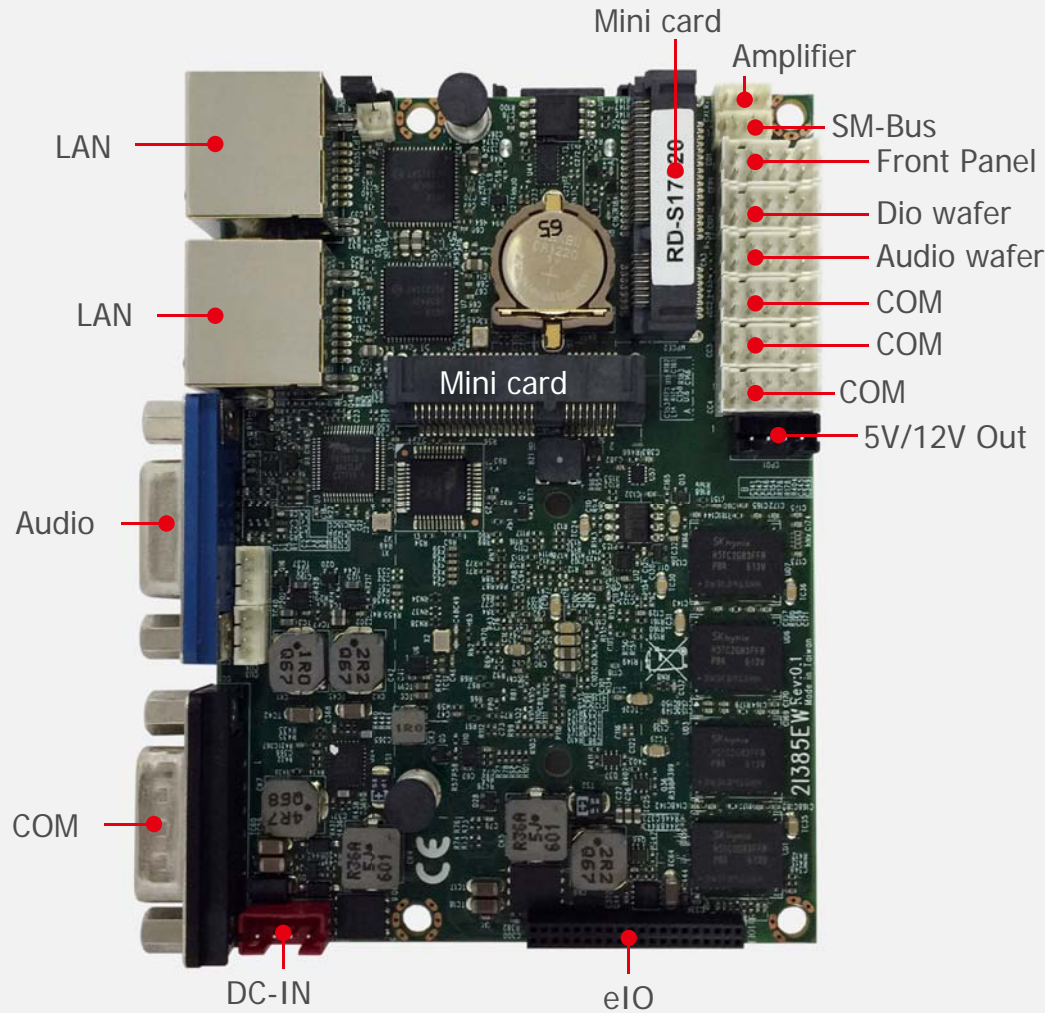
## 21392CW

Compact solution with Rich Expansion for vertical application

- Intel® Apollo Lake N4200 / N3350 / E3950 SoC CPU / chipset
- 1 x DDR3L 1600 Mhz SODIMM, Max up to 8GB
- Display: LVDS & 2 x HDMI (option 2 x Display Port)
- 2 x GbE, 2 x Mini PCIe, 4 x USB 3.0, 3 x USB 2.0
- 2 x COM (3 in 1 RS232/422/485 select by BIOS)
- 4DI/4DO, HD audio, Lex eIO: 2 x PCIe + USB
- Wide Range DC IN +9~36V
- Wide temperature support of -20°C ~ 70°C
- Support 4K UHD resolution content



# Function MAP



## 21385EW

Compact solution with Rich Expansion for vertical application

- Intel® Bay Trail E3825 /E3845/J1900 (Dual Core/Quad Core) SoC CPU / chipset
- On board DDR3L 2GB / 4GB
- Display: VGA
- 2 x GbE, 2 x Mini PCIe, 4 x USB 2.0
- 2 x COM (3 in 1 RS232/422/485 select by BIOS)
- 4DI/4DO, HD audio, 4 x COM, Lex eIO: 2 x PCIe + USB
- Wide Range DC IN +9~36V
- Wide temperature support of -20°C ~ 70°C





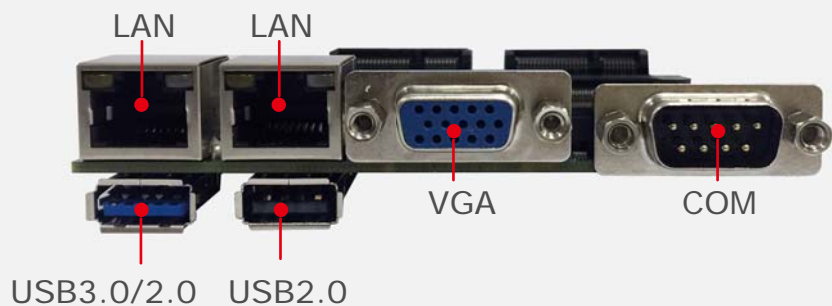
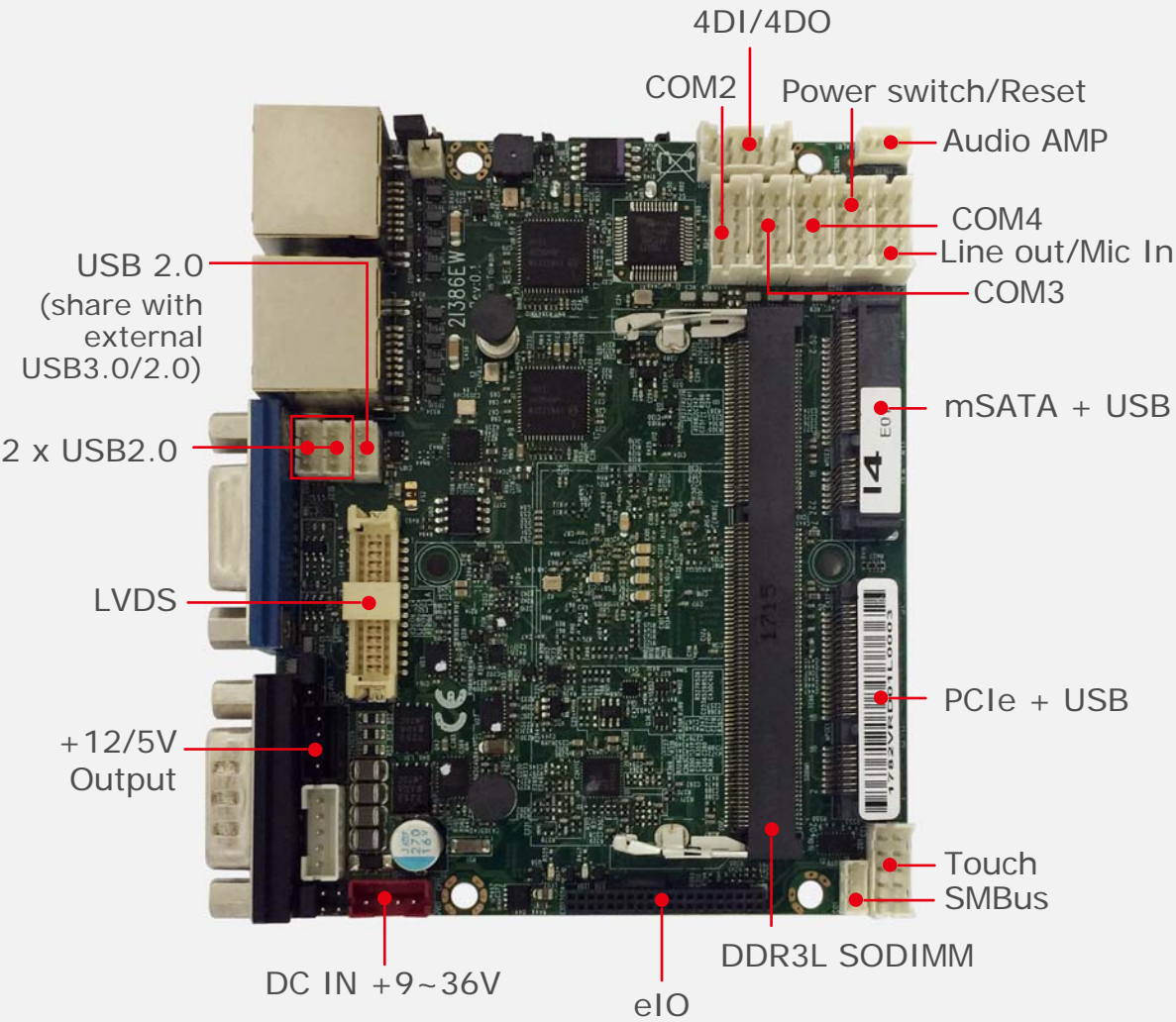
# Function MAP



## 21386EW

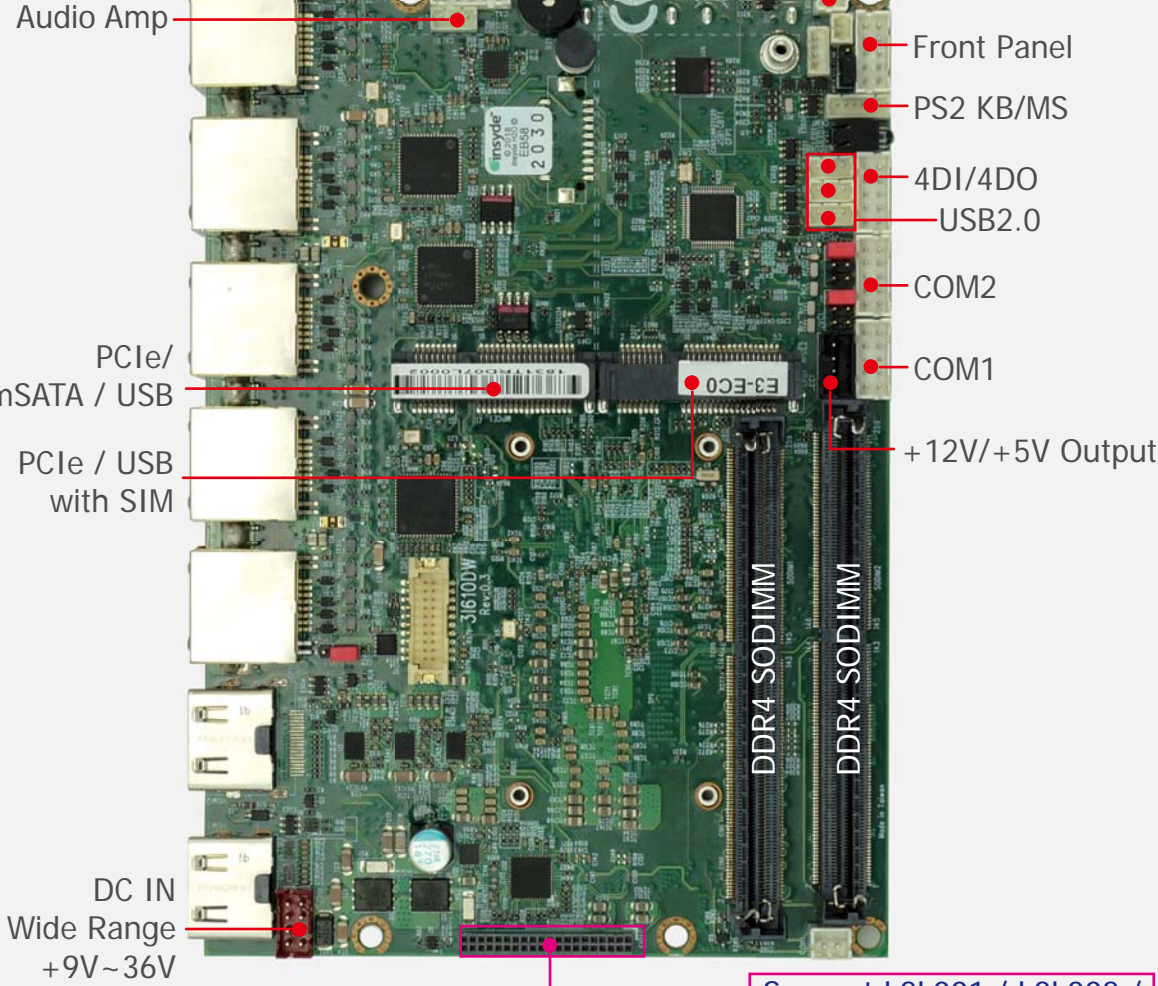
Compact solution with Rich Expansion for vertical application

- Intel® Bay Trail E3845/J1900 (Quad Core) SoC CPU / chipset
- 1 x DDR3L 1333Mhz SODIMM, max up to 8GB
- Display: VGA & LVDS
- 2 x GbE, 2 x Mini PCIe, 1 x USB 3.0, 3 x USB 2.0
- 4 x COM (COM1/COM2: 2 x RS232 / RS422 / 485)  
(COM3/COM4: 2 x RS232)
- 4DI/4DO, HD audio, Lex eIO (2 x PCIe + USB), Touch, Audio AMP
- Wide Range DC IN +9~36V
- Wide temperature support of -20°C ~ 70°C

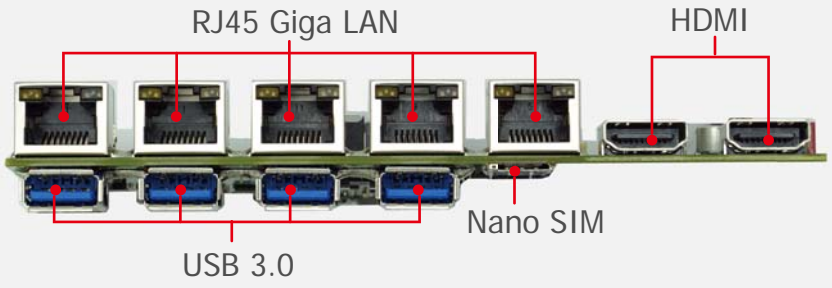


# Function MAP

Audio / Line-In/  
Line-Out / Mic-In      Power Switch



Support L2L001 / L2L002 /  
L2L003 / L2L004 / L2M001  
EIO connector



## 3i610DW

### Complete solution for Networking & IoT Applications

- Intel® Skylake-U / Kaby Lake-U i7 / i5 / i3 / Celeron CPU / chipset
- 2 x DDR4 SODIMM socket, max. up to 32GB
- Display Interface: 2 x HDMI, eDP
- 5 x Intel (4 x I210 IT + 1 x I219LM) GbE, 2 x Mini PCIe, 1 x Nano SIM
- 7 x USB (4 x USB 3.0/2.0 + 3 x USB 2.0)
- HD Audio
- 2 x COM (RS232/422/485)
- 4DI/4DO, HD audio, Lex eIO: PCIe + USB
- Wide Range DC IN +9~36V
- Wide temperature support of -20°C ~ 70°C
- TPM 2.0 / vPro





# LEX eIO Rich Expansion for Vertical Applications

LEX's innovative eIO Extension MBs:

2I390CW / 2I390CW / 2I385EW / 2I386EW / 3I610DW are flexible and integrated various IO cards to help aid efficient development, reduce resources and assist integrators to provide optimized solutions to their customers more quickly.

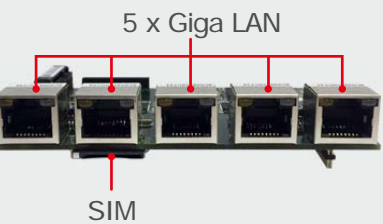
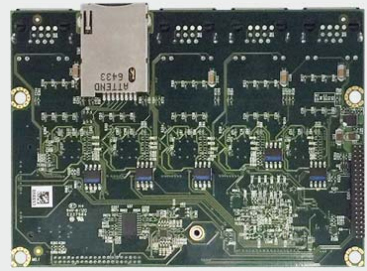
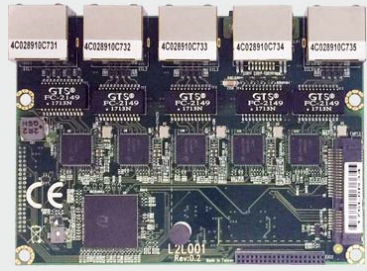
Through the eIO interface, the additional functions with eIO MB can be:  
5-port GbE, 4-port GbE plus Fiber, 4 x PoE with Fiber, 2 x PoE or 1 PoE + Fiber,  
4 x SIM card socket & 4 x mini card PCIe as below:





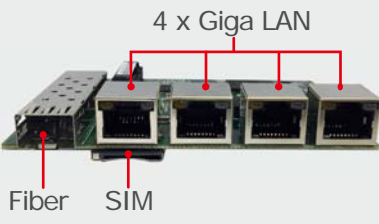
# LEX eIO extension card:

## L2L001



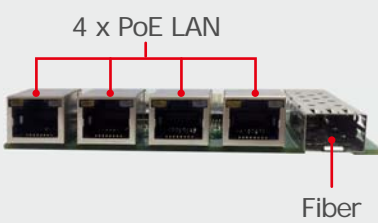
- 5 PCIe Giga LAN
- Intel I210-IT / I211-AT
- 1 Mini PCI Express socket.
- USB and PCIe (Option, share fifth LAN port)
- SIM-Push-Push
- Dimension: 102 x 73mm

## L2L002



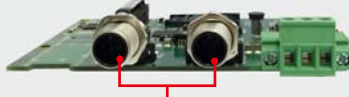
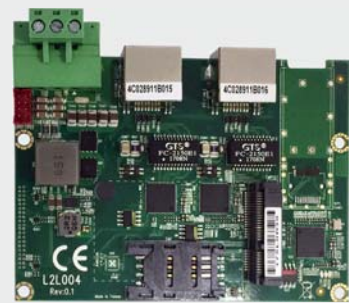
- 4 PCIe Giga LAN
- Intel I210-IT / I211-AT
- 1 port 1000Base-SX Fiber.
- 1 Mini PCI Express socket.
- USB and PCIe (Option, share Fiber LAN port)
- SIM-Push-Push
- Dimension: 102 x 73 mm

## L2L003



- 4 x PoE Giga LAN, 1 x Fiber LAN
- Power: Wide Range +9V ~+36V
- Dimension: 102mm x 73 mm

## L2L004



- 2 x PoE Giga LAN M12 type
- 1 x Fiber LAN (Optional to 1 x PoE LAN)
- 1 x Full Size Mini card USB interface
- 1 x SIM socket
- Power: Wide Range +9V ~+36V
- Dimension: 102mm x 73 mm

## L2M001



- 4 Mini PCI Express socket (full size)
- Support USB and PCIe, SIM-Push-Push
- For option: 2 x USB 3.0
- Dimension: 117 x 73 mm

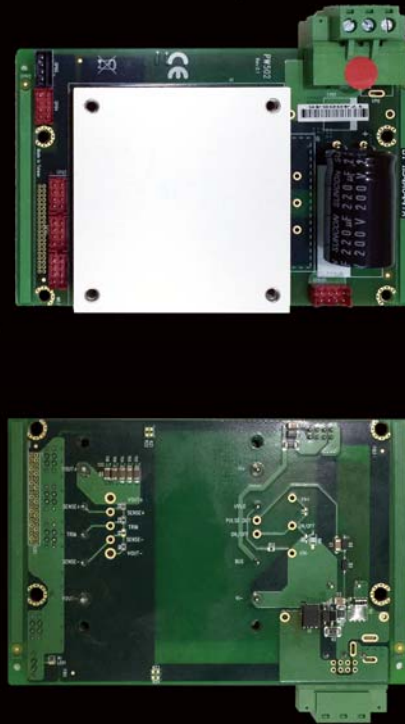
# LEX eIO extension card & Power board:

PW501



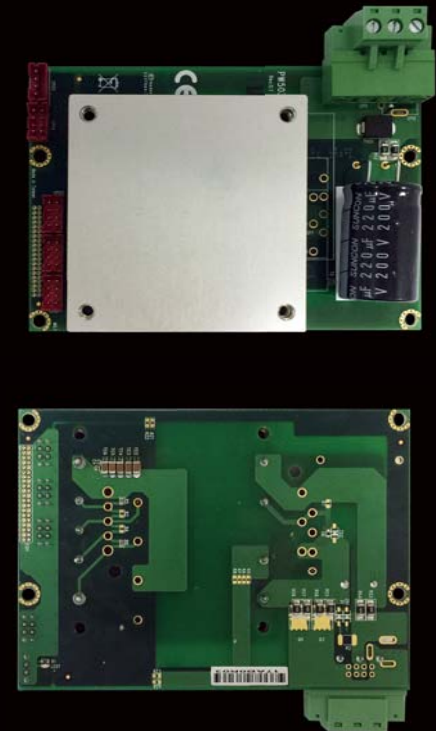
- Wide Range Power board
- Input: DC IN 18V~36V / DC IN 18V~75V / DC IN 9V~36V
- Output: 4 x +12V DC output (Optional to 24V DC output)
- Power: 120W
- Dimension: 73 x 45 mm (power board size)

PW502



- Wide Range Power board & power supply
- Input Voltage: 18V~75V, 9V~36V or 16.6V~154V
- Output: 4 x +12V DC output (Optional to 24V DC output)
- Operating base plate temperature -40°C to +100 °C
- Isolation voltage: 3000V
- Power: 200W
- Dimension: 102 x 73 mm (power board size)

PW503



- Wide range Power board & Power Supply
- Input Voltage: 43V~160V
- Output: 5 x +12V DC output
- Isolation voltage: 3000V
- Power: 200W
- Dimension: 102 x 73 mm (power board size)







TERA + 2I390CW + L2M001



TERA + 2I390CW + L2L001



TERA + 2I385EW + L2L002

## TERA Series

Dimension: 56.5H x 145W x 106.2D mm

- Compact heat-dissipating System
- Robust & Powerful Fanless Embedded solution







2I390CW + L2L001

## MIRO-2 Series

Dimension: 72 H x 140 W x 92 D mm

- Industrial networking solution
- Powerful Fanless Din-Rail solution



Data Sheet (PDF)



21390CW + L2L001



21390CW + L2L002

## BLADE Series

Dimension: 63 H x 150 W x 80.8 D mm

- Compact heat-dissipating System
- Robust & Powerful Fanless Embedded solution







TASK + 3I610DW + L2L001

## TASK Series

Dimension: 77H x 210W x 125D mm

- Super Excellent heat-dissipating System
- Robust & Powerful Fanless Embedded solution



Data Sheet (PDF)